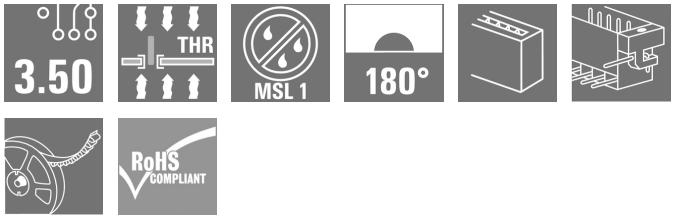
SL-SMT 3.50/05/180LF 1.5SN BK RL

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 26
D-32758 Detmold
Germany

www.weidmueller.com

Product image





High-temperature-resistant male header, 3.50 mm pitch.

- **Plugging direction parallel (90°), straight 180° or angled (135°) to PCB**
- **Housing variants: closed side (G), screw flange (F), solder flange (LF) or snap-on solder flange (RF)**
- **Optimised for the SMT process**
- **Pin length 3.2 mm universal for all soldering methods**
- **Pin length 1.5 mm optimised for reflow soldering methods**
- **Packed either in a box (BX) or tape-on-reel (RL)**
- **Male header can be coded**

General ordering data

Version	PCB plug-in connector, male header, Solder flange, THT/THR solder connection, 3.50 mm, Number of poles: 5, 180°, Solder pin length (l): 1.5 mm, tinned, black, Tape
Order No.	1805250000
Type	SL-SMT 3.50/05/180LF 1.5SN BK RL
GTIN (EAN)	4032248269525
Qty.	265 pc(s).
Product data	IEC: 320 V / 15 A UL: 300 V / 10 A
Packaging	Tape

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Technical data

Dimensions and weights

Depth	7.5 mm	Depth (inches)	0.295 inch
Height	12.6 mm	Height (inches)	0.496 inch
Height of lowest version	11.1 mm	Width	24.5 mm
Width (inches)	0.965 inch	Net weight	3.743 g

System specifications

Product family	OMNIMATE Signal - series BL/SL 3.50	Type of connection	Board connection
Mounting onto the PCB	THT/THR solder connection	Pitch in mm (P)	3.5 mm
Pitch in inches (P)	0.138 "	Outgoing elbow	180°
Number of poles	5	Number of solder pins per pole	1
Solder pin length (l)	1.5 mm	Solder pin length tolerance	0 / -0.3 mm
Solder pin dimensions	d = 1.2 mm, Octagonal	Solder pin dimensions = d tolerance	0 / -0,03 mm
Solder eyelet hole diameter (D)	1.4 mm	Solder eyelet hole diameter tolerance (D)	+ 0,1 mm
Outside diameter of solder pad	2.3 mm	Template aperture diameter	2.1 mm
L1 in mm	14 mm	L1 in inches	0.551 "
Number of rows	1	Pin series quantity	1
Touch-safe protection acc. to DIN VDE 57 106	finger-safe plugged/ back-of-hand-safe unplugged	Touch-safe protection acc. to DIN VDE 0470	IP20 plugged/ IP10 unplugged
Protection degree	IP10	Volume resistance	≤5 mΩ
Can be coded	Yes	Plugging cycles	25
Plugging force/pole, max.	6 N	Pulling force/pole, max.	6 N

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIa
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	Cu-alloy
Contact surface	tinned	Layer structure of solder connection	2...3 µm Ni / 5...7 µm Sn
Layer structure of plug contact	2...3 µm Ni / 5...7 µm Sn	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	15 A
Rated current, max. number of poles (Tu=20°C)	12 A	Rated current, min. number of poles (Tu=40°C)	13 A
Rated current, max. number of poles (Tu=40°C)	10 A	Rated voltage for surge voltage class / pollution degree II/2	320 V
Rated voltage for surge voltage class / pollution degree III/2	160 V	Rated voltage for surge voltage class / pollution degree III/3	160 V
Rated impulse voltage for surge voltage class/ pollution degree II/2	2.5 kV	Rated impulse voltage for surge voltage class/ pollution degree III/2	2.5 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	2.5 kV	Short-time withstand current resistance	3 x 1s with 100 A

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Technical data

Rated data acc. to CSA

Institute (CSA)		Certificate No. (CSA)	200039-1176845
Rated voltage (Use group B / CSA)	300 V	Rated voltage (Use group D / CSA)	300 V
Rated current (Use group B / CSA)	10 A	Rated current (Use group D / CSA)	10 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		

Rated data acc. to UL 1059

Institute (UR)		Certificate No. (UR)	E60693
Rated voltage (Use group B / UL 1059)	300 V	Rated voltage (Use group D / UL 1059)	300 V
Rated current (Use group B / UL 1059)	10 A	Rated current (Use group D / UL 1059)	10 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		

Packing

ESD Level packaging	static dissipative	Packaging	Tape
VPE length	331 mm	VPE width	331 mm
VPE height	52 mm	Tape depth (T2)	16.5 mm
Tape width (W)	44 mm	Tape pocket depth (K0)	16 mm
Tape pocket height (A0)	7.8 mm	Tape pocket width (B0)	33.2 mm
Tape pocket separation (P1)	16 mm	Tape hole separation (E)	1.75 mm
Tape pocket separation (F)	20.2 mm	Tape reel diameter ⌀ (A)	330 mm
Surface resistance	Rs = 10^9 - 10^{12} Ω	Width Pick & Place Pad (W_{PPP})	6.8 mm
Length Pick & Place Pad (L_{PPP})	12.65 mm	Diameter of the withdrawal surface (ø D_{max})	5 mm
Protrusion 1 Pick & Place Pad ($L_{01\ (PPP)}$)	2.5 mm	Protrusion 2 Pick & Place Pad ($P_{02\ (PPP)}$)	2.7 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ETIM 9.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01
ECLASS 12.0	27-46-02-01	ECLASS 13.0	27-46-02-01
ECLASS 14.0	27-46-02-01		

Environmental Product Compliance

REACH SVHC	/
RoHS Compliance Status	Compliant without exemption

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Technical data

Important note

IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.
Notes	• Gold-plated contact surfaces on request • Rated current related to rated cross-section & min. No. of poles. • Diameter of solder eyelet D = 1.4+0.1mm • Solder eyelet diameter D = 1.5 + 0.1 mm, from 9 poles • P on drawing = pitch • Rated data refer only to the component itself. Clearance and creepage distances to other components are to be designed in accordance with the relevant application standards. • In accordance with IEC 61984, OMNIMATE-connectors are connectors without breaking capacity (COC). During designated use, connectors are not allowed to be engaged or disengaged when live or under load • Long term storage of the product with average temperature of 50 °C and maximum humidity 70%, 36 months

Approvals

Approvals	
ROHS	Conform
UL File Number Search	UL Website
Certificate No. (UR)	E60693

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Technical data

Downloads

Approval/Certificate/Document of Conformity	Declaration of the Manufacturer
Engineering Data	CAD data – STEP
Product Change Notification	PCN_2015_208_PL30X_SC-SMT_SL_SMT_3.xx_5.xx_neue_Tapeverpackung_Step_3_DE PCN_2015_208_PL30X_SC-SMT_SL_SMT_3.xx_5.xx_new_Tape_Packaging_Step_3_EN Changeover to ESD bags for "Tape on Reel" products Umstellung auf ESD-Beutel bei „Tape on Reel" Produkten
Catalogues	Catalogues in PDF-format
Brochures	FL DRIVES EN MB SMT EN FL DRIVES DE MB DEVICE MANUF. EN FL BUILDING SAFETY EN FL APPL LED LIGHTING EN FL INDUSTR.CONTROLS EN FL MACHINE SAFETY EN FL HEATING ELECTR EN FL APPL_INVERTER EN FL_BASE_STATION_EN FL ELEVATOR EN FL POWER SUPPLY EN FL 72H SAMPLE SER EN PO OMNIMATE EN PO OMNIMATE EN
White paper surface mount technology	Download Whitepaper

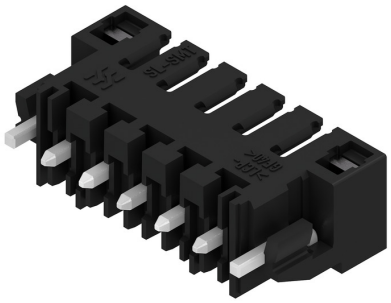
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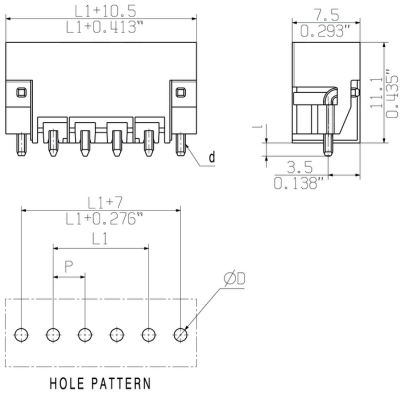
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Drawings

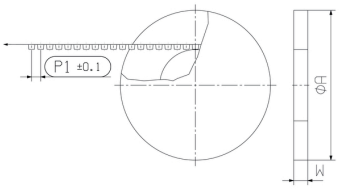
Product image



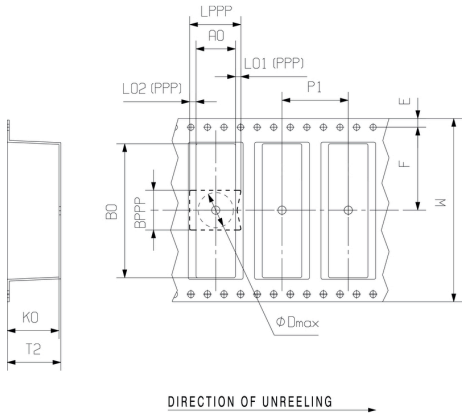
Dimensional drawing



Dimensional drawing



Dimensional drawing



Example of use

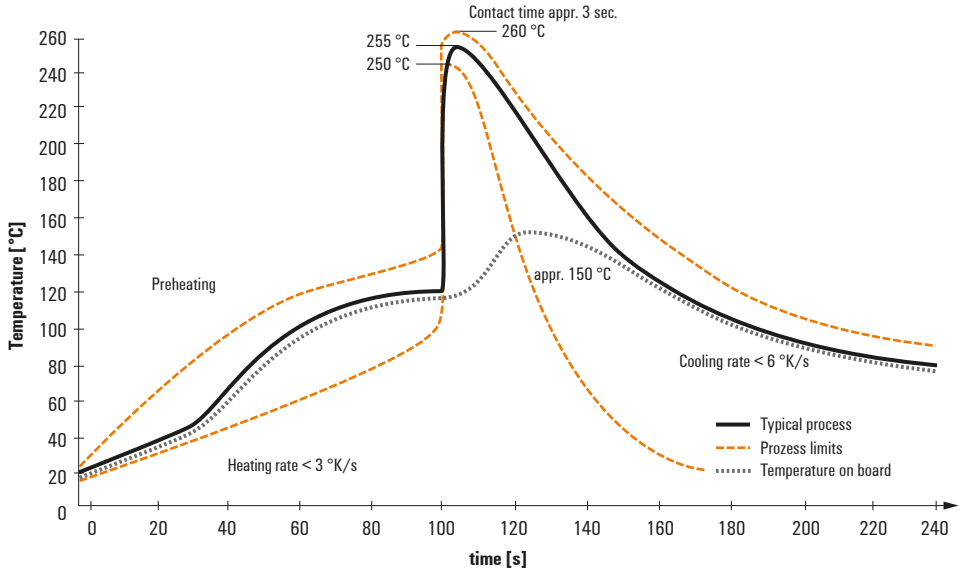


Wave Solder Profile

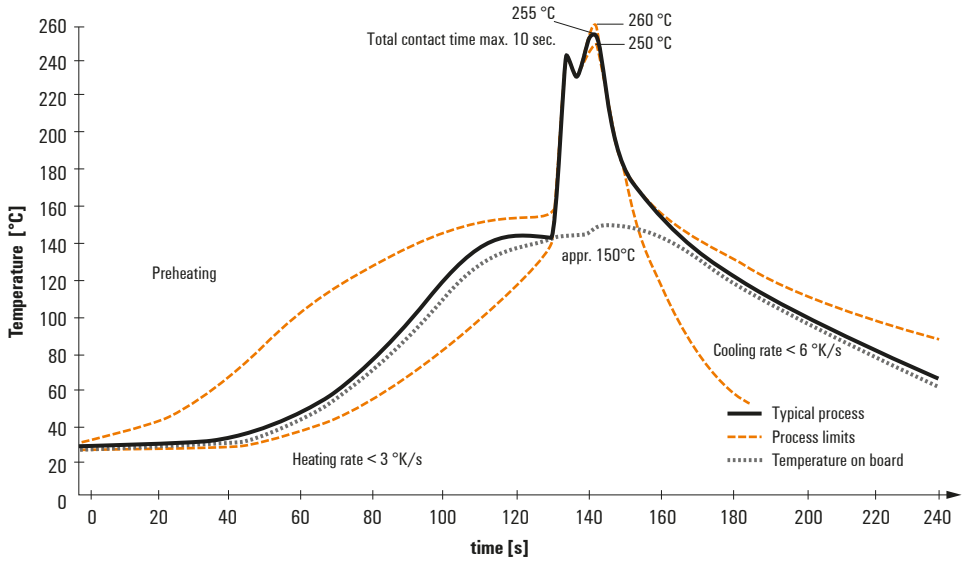
Recommended wave solderding profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:
- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

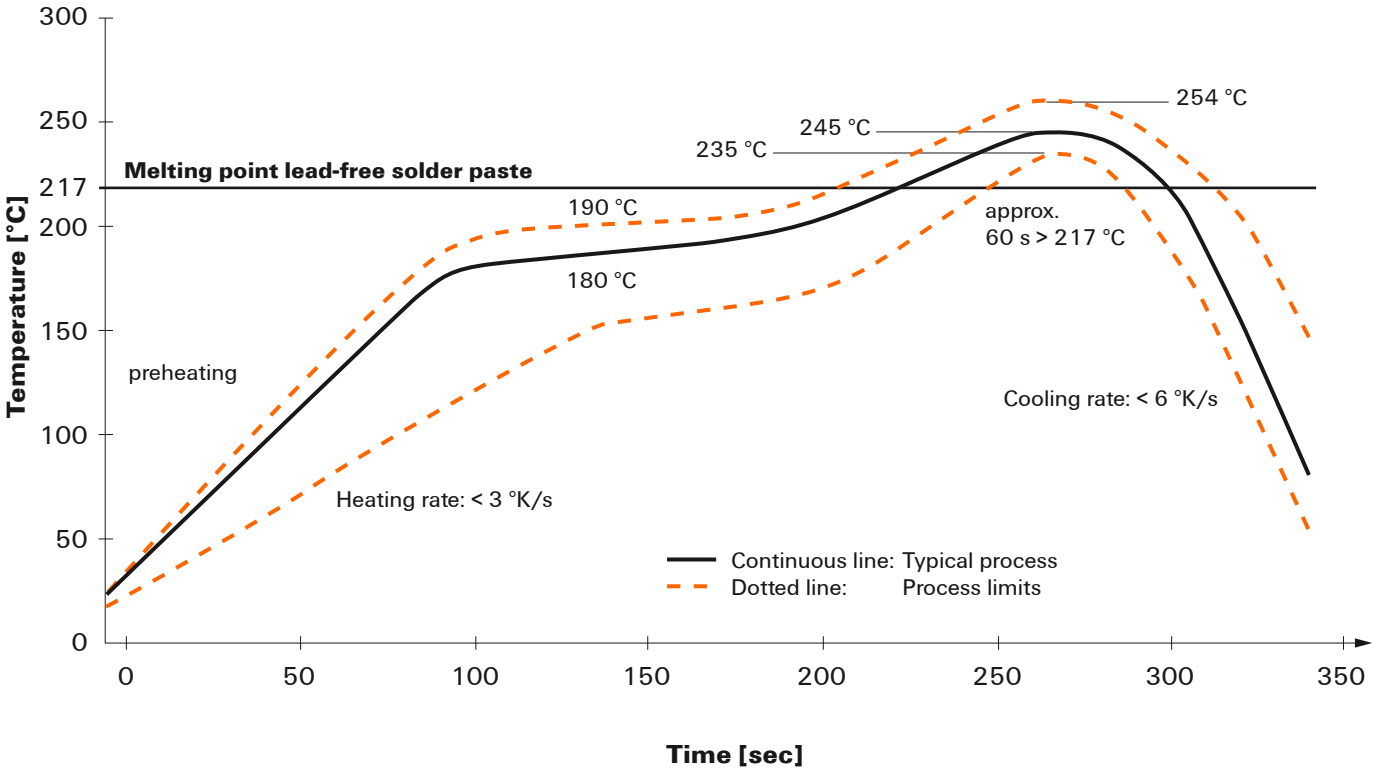
The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Reflow Solder Profile

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:
- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically ≤ +3K/s. In parallel the solder paste is ‚activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at ≥ -6K/s solder is cured. Board and components cool down while avoiding cold cracks.

We reserve the right to make technical changes.